

PRODUCTION DATA SHEET

DESCRIPTION

The LX7201 is an integrated The downstream port. line as a downstream connection.

The 47 pF capacitor completes the Universal Serial Bus (USB) line high frequency filter and controls the termination device with an EMI filter edge rate of the USB signals. The and ESD protection diodes. This LX7201 protects both D+ and D- data device offers a cost effective and lines and the voltage bus from ESD. compact solution for one USB The TVS protection diodes exceed the USB requirements of IEC61000-4-2, level 4, specification requires line termination 15kV (air discharge) and 8kV (contact resistors on both the D+ and D- lines. discharge). The integrated configuration These resistors ensure signal integrity of the LX7201 minimizes board space by matching the cable impedance to and allows for ideal placement near the that of the differential driver. The connector. The LX7201 is ideal for use $15K\Omega$ pull-down resistors identify the in USB hubs, peripherals and portable appliances.

IMPORTANT: For the most current data, consult MICROSEMI's website: http://www.microsemi.com

,	PACKAGE ORDER INFO					
	T _J (°C)	SF Plastic 6-Pin SOT23	Package Marking	Tape & Reel Quantity (Reel Size)		
	-40 to 125	LX7201-15ISF	2011	3K (7inches)		
	-40 to 125	0 to 125 LX7201-22ISF		Six (/iliches)		

Note: Append the letter "T" to the part number For Tape & Reel Ordering

KEY FEATURES

- Bi-directional EMI/RFI Low-Pass Filter
- Line Termination with Integrated **ESD Protection**
- Low TVS Operating Voltage (5.25V)
- Low Leakage Current
- Integrated Single Die Construction
- Available With 15 or 22Ω Series Resistance
- Crosses from Semtech STF201

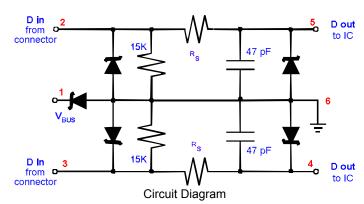
APPLICATIONS

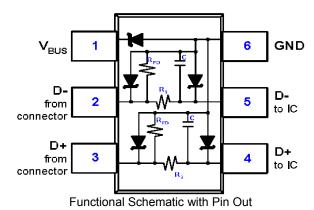
- USB 1.1 and USB 2.0 Full **Speed Compliant**
- Peripherals
- **Printers**
- Monitors
- Servers. Desktops and **Notebook Computers**
- **Digital Cameras**

BENEFITS

- Filter response characterized up to 6 GHz
- <2dB insertion loss in the pass hand
- >20dB attenuation in the 800-900 MHz range
- >12dB attenuation in the WLAN frequencies of 2.4GHz and 5.0-6.0 GHz

PRODUCT HIGHLIGHT







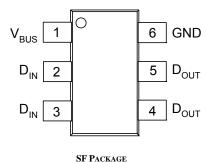
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ABSOLUTE MAXIMUM RATINGS

Steady State Power	100mW
ESD Air Discharge per IEC61000-4-2	16kV
ESD Contact Discharge per IEC61000-4-2	10kV
Lead Soldering Temperature (10 Seconds)	260°C
Operating Temperature	40°C to +125°C
Storage Temperature Range	55°C to +150°C

Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

PACKAGE PIN OUT



(Top View)

THERMAL DATA

Plastic SOT23 6-Pin

THERMAL RESISTANCE-JUNCTION TO CASE, θ_{JC}	62 °C/W	
THERMAL RESISTANCE-JUNCTION TO AMBIENT, θ_{JA}	96 °C/W	

Junction Temperature Calculation: $T_J = T_A + (P_D \times \theta_{JA})$.

The θ_{JA} numbers are guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.

	FUNCTIONAL PIN DESCRIPTION				
Name	Description				
VBUS	Bus Voltage				
DIN	Data In				
GND	Ground				
DOUT	Data Out				

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, the following specifications apply over the operating ambient temperature -40°C $\leq T_A \leq$ +125°C except where otherwise noted.

Parameter	Symbol Test Conditions		LX7201-xx			Units
r ai ailletei	Symbol	yillboi lest colluitions		Тур	Max	Units
Stand-Off Voltage	VR_{WM}				5.25	V
Breakdown Voltage	V_{BR}	IR = 1mA	6			V
Leakage Current	I _R	VRWM = 5.25V, T = 25°C			1	μΑ
Series Resistance (-15)	Rs	Each Line	13.5	15	16.5	Ω
Series Resistance (-22)	Rs	Each Line	19.8	22	24.2	Ω
Temperature Coefficient of R _S	T _{COEFF}	Each Line		200		ppm
Pull Down Resistance	R_{PD}	Each Line	13.5	15	16.5	ΚΩ
Capacitor	С	Each Line		47		pF
Total Capacitance	Стот	Between I/O Pins and Ground, Each Device VR = 0V, f = 1MHz	54	60	66	pF

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APPLICATION CIRCUITS

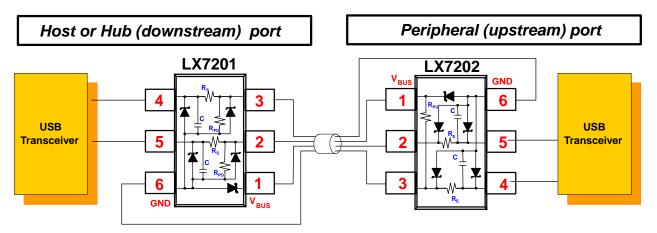


Figure 1 - Typical Application

APPLICATION INFORMATION

The LX7201 meets the requirements of the USB v1.1 and USB 2.0 Full Speed specification for device termination, EMI filtering and ESD protection. The R_S resistor provides the proper signal termination; the 47pF capacitor controls the signal rise and fall slew; the TVS diodes protect the IC from ESD damage; and the total capacitance and resistance creates a low pass filter eliminating the high frequency energy from the circuit.

Device Connection:

- Voltage Supply (V_{BUS}) is connected to Pin 1
- Ground is connected to Pin 6
- D+ from the connector is routed to Pin 2 and out of Pin 5.
- D- from the connector is routed to Pin 3 and out of Pin 4.

ELECTROMAGNETIC EMISSION AND SUSCEPTABILITY

FCC Part 15 sets limits for maximum allowable EM emission and susceptibility. There are two types of emissions. Conducted emissions with frequency of emission of 0.45 to 30 MHz and Radiated emissions with frequency of emission of 30 MHz to 40 GHz. All digital computing devices including the peripheral devices must comply. Examples of peripheral devices include terminals, printers, external floppy disk drives and other data storage devices, video monitors,

keyboards, control cards, interface boards, external memory expansion cards and other input/output devices that may or may not contain digital circuitry. LX7201 is optimized to minimize the radiated EMI which is the primary concern in devices using USB. Refer to the typical filter response curve for the attenuation characteristics of LX7201 over the frequency range of 30KHz to 6GHz.



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CHARACTERISTIC CURVES

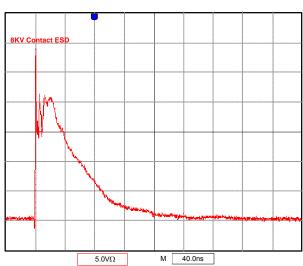


Figure 2 – 8KV ESD input pulse as per IEC61000-4-2. Vertical scale is equivalent to 5A/div.

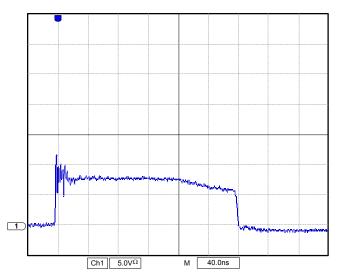


Figure 3 – Clamping Characteristics when device subjected to an 8 KV ESD pulse.

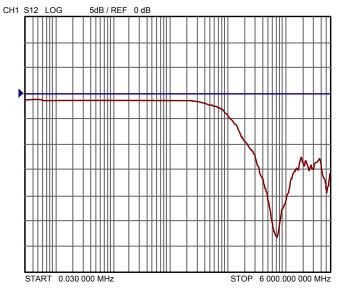


Figure 4 – Frequency response curve. Low insertion loss in the pass band and -20dB attenuation at 800-900 MHz. Better than -10dB attenuation at the WLAN frequencies of 2.4 and 5.0-6.0 GHz.

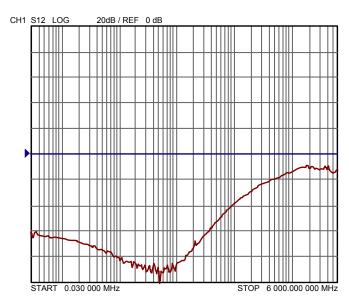


Figure 5 – Analog Crosstalk between the two datalines Dand D+

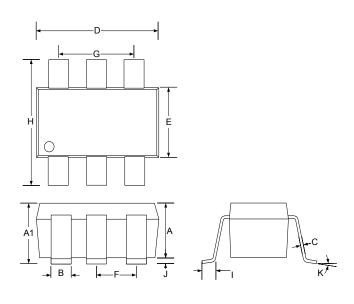


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PACKAGE DIMENSIONS

SF

6-Pin SOT-23 Package

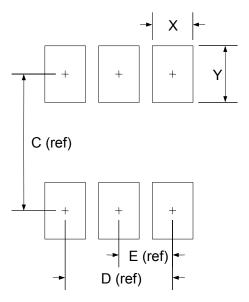


	MILLIMETERS		INCHES			
Dim	MIN	MAX	MIN	MAX		
Α	0.90	1.30	0.035	0.051		
A1	0.90	1.45	0.035	0.057		
В	0.25	0.50	0.010	0.020		
С	0.09	0.20	0.004	0.008		
D	2.80	3.10	0.110	0.122		
E	1.50	1.75	0.059	0.069		
F	0.95 BSC		0.038 BSC			
G	1.90	1.90 BSC		0.075 BSC		
Н	2.60	3.00	0.102	0.118		
I	0.35	0.55	0.014	0.022		
J	0.00	0.15	0.000	0.006		
K	10° MAX		10° MAX			

Note:

 Dimensions do not include mold flash or protrusions; these shall not exceed 0.155mm(.006") on any side. Lead dimension shall not include solder coverage.

Recommended Footprint



	MILLIN	MILLIMETERS		INCHES		
Dim	MIN	MAX	MIN	MAX		
С	-	2.40	-	0.094		
D	-	1.90	-	0.074		
Е	-	0.95	-	0.037		
Х	-	0.70	-	0.028		
Υ	_	1.00	_	0.039		



LX7201-xx

EMI Filter & ESD Protection for Down Stream USB Ports

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NOTES

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